

MOISTURE SENSITIVITY LEVEL FOR SURFACE MOUNT PACKAGE

PACKAGE CATEGORY	DESCRIPTION (SURFACE MOUNT PACKAGE)	LTC Designated Package Codes	MSL Solder Plate Profile	MSL Pb Free Profile	Dry Pack Required	
MSOP	8 LEAD MSOP	MS8	1	1	No	
	10, 12, 16 LEAD MSOP	MS	1	1	No	
	8 LEAD MSOP EXPOSED DIE PAD	MS8E	1	1	No	
	10, 12, 16 LEAD MSOP EXPOSED DIE PAD	MSE	1	1	No	
SO	8 LEAD SO	S8	1	1	No	
	14 LEAD SO	S	1	1	No	
	16 LEAD SO (NARROW)	S	1	1	No	
	16, 18, 20, 24, 28 LEAD SO (WIDE)	SW	1	1	No	
SOT-223	3 LEAD SOT-223	ST	1	1	No	
SOT	3 LEAD SOT-23	S3	1	1	No	
TSOT	5 LEAD TSOT	S5	1	1	No	
	6 LEAD TSOT	S6	1	1	No	
	8 LEAD TSOT	TS8	1	1	No	
SC70	6 LEAD SC70	SC6	1	1	No	
	8 LEAD SC70	SC8	1	1	No	
TSSOP	14, 20, 28 LEAD TSSOP (4.4mm)	F	1	1	No	
	48 LEAD TSSOP (6.1mm)	FW	1	1	No	
	56 LEAD TSSOP (6.1mm)	FW	1	TBQ	TBD	
	16, 20, 24, 28, 38 LEAD TSSOP (4.4mm) EXPOSED DIE PAD	FE	1	1	No	
SSOP	16, 20, 24, 28 LEAD SSOP (NARROW)	GN	1	1	No	
	16, 20, 24, 28, 36, 44 LEAD SSOP	G	1	1	No	
	36, 44 LEAD SSOP (WIDE)	GW	1	1	No	
DFN	3, 4, 6, 8 LEAD DFN (2mm x 2mm)	DC	1	1	No	
	6, 8 LEAD DFN (2mm x 3mm)	DCB	1	1	No	
	8, 10, 12 LEAD DFN (3mm x 3mm)	DD, DDMA	1	1	No	
	8, 10, 12 LEAD DFN (3mm x 2mm)	DDB	1	1	No	
	12, 14, 16 LEAD DFN (4mm x 3mm)	DE, DE14MA, UE	1	1	No	
	16 LEAD (3mm x 4mm)	DE16MA	1	1	No	
	12 LEAD DFN (4mm x 4mm)	DF	1	1	No	
	16 LEAD DFN (5mm x 5mm)	DH	1	1	No	
	16 LEAD DFN (5mm x 3mm)	DHC	1	1	No	
	16 LEAD DFN (5mm x 4mm)	DHD	1	1	No	
	22 LEAD DFN (6mm x 3mm)	DJC	1	1	No	
	32 LEAD DFN (7mm x 4mm)	DKD	1	1	No	
	UTDFN	8 LEAD UTDFN (2mm x 2mm)	KC	1	1	No
		10 LEAD UTDFN (3mm x 3mm)	KD	1	1	No
		14 LEAD UTDFN (4mm x 4mm)	KE	1	1	No
QFN	16, 20 LEAD QFN (3mm x 3mm)	UD	1	1	No	
	20, 24 LEAD QFN (3mm x 4mm)	UDC	1	1	No	
	24 LEAD QFN (3mm x 5mm)	UDD	1	1	No	
	16, 20, 24, 28 LEAD QFN (4mm x 4mm)	UF	1	1	No	
	20, 24, 28 LEAD QFN (4mm x 5mm)	UFD	1	1	No	
	38 LEAD QFN (4mm x 6mm)	UFE	1	1	No	
	34 LEAD QFN (4mm x 7mm)	UFF	1	1	No	
	20, 24, 32, 40 LEAD QFN (5mm x 5mm)	UH	1	1	No	
	28 LEAD QFN (5mm x 6mm)	UHE28MA	1	1	No	
	36 LEAD QFN (5mm x 6mm)	UHE	1	1	No	
	38 LEAD QFN (5mm x 6mm)	UHF	1	1	No	
	39, 52 LEAD (5mm x 8mm)	UHG	1	1	No	
	56 LEAD QFN (5mm x 9mm)	UHH	1	1	No	
	40 LEAD QFN (6mm x 6mm)	UJ	1	1	No	
	44, 48 LEAD QFN (7mm x 7mm)	UK	1	1	No	
	52 LEAD QFN (7mm x 8mm)	UKG	1	1	No	
	52 LEAD MULTIPAD (7mm x 8mm)	WKG	1	1	No	
	64 LEAD QFN (7mm x 9mm)	UKH	1	1	No	
	64 LEAD QFN (9mm x 9mm)	UP	1	1	No	
	64 LEAD MULTIPAD (9mm x 9mm)	WP	1	1	No	
UTQFN	16, 20 LEAD UTQFN (3mm x 3mm)	PD	1	1	No	
	20 LEAD UTQFN (3mm x 4mm)	PDC	1	1	No	
	24 LEAD UTQFN (4mm x 4mm)	PF	1	1	No	
LQFP	48 LEAD LQFP (7mm x 7mm) +	LX	3	3	Yes	
	48 LEAD eLQFP (7mm x 7mm) +	LXE	3	3	Yes	
LGA	21 LEAD LGA (6.25mm x 6.25mm x 2.32mm) +	V	3	3	Yes	
	32, 35 LEAD LGA (11.25mm x 6.25mm x 2.82mm) +	V	3	3	Yes	
	40 LEAD LGA (11.25mm x 6.25mm x 4.32mm) +	V	3	3	Yes	
	50, 56 LEAD LGA (11.25mm x 9mm x 2.82mm) +	V	3	3	Yes	
	81 LEAD LGA (11.25mm x 11.25mm x 2.32mm) +	V	3	3	Yes	
	45 LEAD LGA (11.25mm x 9mm x 4.32mm) +	V	3	3	Yes	
	66 LEAD LGA (15mm x 9mm x 2.32mm) +	V	3	3	Yes	
	28, 68, 69, 71 LEAD LGA (15mm x 9mm x 2.82mm) +	V	3	3	Yes	
	66, 70, 84 LEAD LGA (15mm x 9mm x 4.32) +	V	3	3	Yes	
	108 LEAD LGA (15mm x 11.25mm x 2.32mm) +	V	3	3	Yes	
	32 LEAD LGA (15mm x 11.25mm x 2.82) +	V	3	3	Yes	
	104, 118, 121, 133, 141, 144 LEAD LGA (15mm x 15mm x 2.82mm) +	V	3	3	Yes	
	113, 133 LEAD LGA (15mm x 15mm x 4.32mm) +	V	3	3	Yes	
	208 LEAD LGA (22mm x 15mm x 2.82mm) +	V	3	3	Yes	
	208 LEAD LGA (22mm x 15mm x 4.32mm) +	V	3	3	Yes	
	100 LEAD SiPLGA (16mm x 16mm x 2.01mm) +	V	3	3	Yes	
DD PAK	3, 5, 7 LEAD DD PAK	M, Q, R	1	1	No	
NOTES:	TBQ = To Be Qualified + = Dry Pack Per JEDEC J-STD-020C, due to package thickness and volume, peak Reflow Temperature for LGA and DD Pak packages is 245°C for Lead (Pb) Free reflow profiles					